DECLAL ON FOR PATENT APPLICATION (WITH POWER O. .TORNEY)

As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled WAFER BACK SIDE COATING TO BALANCE STRESS FROM PASSIVATION LAYER ON FRONT OF WAFER AND BE USED AS A DIE ATTACH ADHESIVE, the specification of which (check one):

⊠ is attached hereto.	Triand Control and Indian			
□ was filed on as U □ was filed on as U	United States application serial no.	and was amended on and was amended under PCT Article 19 on		
d was filed oil as i	The mational application to.	and was amended under PC1 Article 19 on	 •	
I hereby state that I have reviewed	and understand the contents of the above-	identified specification, including the claims, as ame	ended by any an	nendment
referred to above.				
I acknowledge the duty to disclose	to the U.S. Potent and Trademark Office	all information known to me to be material to the pa	tantahilini af th	o subicat
•	"materiality" is defined in Title 37, Code	•	tentability of th	e subject
		3 2.00.		
		§ 119(a)-(d) or § 365(b) of any foreign application(s)		
		t one country other than the United States of Americ ontinuation page any foreign application for patent of		
		Inited States of America having a filing date before		
which priority is claimed.	and at reast one teams of the name are t	raised duties of raiseriou having a fining date before	unit of the appri	ication(s) on
Prior foreign/PCT application(s):			n to to out	
			Priority Clair	ned
(number)	(country)	(day/month/year filed)	Yes	No
		•		
(number)	(acustru)	(day/month/year filed)	- Van	- N-
· (namber)	(country)	(day/monur/year med)	Yes	No
I hereby claim the benefit under Ti	tle 35. United States Code. § 120 of any L	Inited States application(s) or § 365(c) of PCT interp	national applica	tion(s)
(application serial no.)	(filing date)	(status - pending, patented of	r abandoned)	
. (application serial no.)				
. (application serial lio.)	(filing date)	(status - pending, patented or	: abandoned)	
I hereby claim the benefit under Tit	le 35, United States Code, § 119(e) of any	United States provisional application(s) listed below	» :	
(provisional application no.)	(filing date)			
I hereby appoint the following Regis therewith:	tered Practitioners to prosecute this applic	ation and to transact all business in the Patent and T	rademark Offic	ce connected
David V. Trask, Reg. No. 22,012	William S. Britt, Reg. No. 20,	NO Laurinea B. Band Ban No. 20	640	
Joseph A. Walkowski, Reg. No. 28,			349	
Allen C. Turner, Reg. No. 33,041	Edgar R. Cataxinos, Reg. No.			
Bruce E. Hayden, Reg. No. 35,539	Brick G. Power, Reg. No. 38,5			
Devin R. Jensen, Reg. No. 44,805	Krista Weber Powell, Reg. No.		Shawn G	6. Hansen,
Reg. No. 42,627	Bretton L. Crockett, Reg. No.		•	
Bradley B. Jensen, Reg. No. 46,801 Michael L. Lynch, Reg. No. 30,871	Andrew F. Nilles, Reg. No. 47 Charles B. Brantley II, Reg. No.		7,628	
	Charles D. Diamicy II, Reg. 14	. 50,000		
Address all correspondence to:	James R. Duzan, telephone no. (801) 53	2-1922.		
	TraskBritt P.O. BOX 2550			
	Salt Lake City, Utah 84110			
	• /			
I hereby declare that all statements m	ade herein of my own knowledge are true	and that all statements made on information and be	lief are believe	d to be true
and further that these statements were m	age with the knowledge that willful false;	statements and the like so made are punishable by fi	ne or imprison	ment, or

2-11-02

Post Office Address: 450 Grove SAtreet, #409, Boise, ID 83702

Full name of first joint inventor: Michael E-Connell

issued thereon.

DECLARATION FOR PATENT APPLICATION (continuation page)

Invention title: WAFER BACK SIDE COATING TO BALANCE STRESS FROM PASSIVATION LAYER ON FRONT OF WAFER AND BE USED AS A DIE ATTACH ADHESIVE

Inventor name(s) appearing on first declaration page: Michael E. Connell

🛮 Additional original, first and joint inventor(s):

Full name of second joint inventor: Tongbi Jiang

Inventor's signature

Residence: Boise, Idaho

Citizenship: U.S.A.

Post Office Address: 12036 W. Patrina Drive, Boise, ID 83713

Date ___

2/11/02